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Cai et al.

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(54) **MIDDLE FRAME MEMBER AND METHOD FOR MANUFACTURING MIDDLE FRAME MEMBER**

(58) **Field of Classification Search**
CPC combination set(s) only.
See application file for complete search history.

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(57) **ABSTRACT**

Embodiments of the present disclosure provide a middle frame member including: a middle frame substrate body; a first metal layer, attached to a first area of the middle frame substrate body, where a coefficient of heat conductivity of the first metal layer is greater than a coefficient of heat conductivity of the middle frame substrate body, the first area includes all or a part of an outer surface of the middle frame substrate body, and the first metal layer is used to conduct, to the entire first metal and the middle frame substrate body, heat generated by at least one of the components that is in contact with or adjacent to the first metal layer; and a passivated insulation layer, attached to a surface of the first metal layer.

16 Claims, 13 Drawing Sheets

